# VALQUA Semiconductor Industry Products

# FLUORITZ ™-TR

## High Performance FFKM

## Product & Benefits

FLUORITZ<sup>TM</sup> –TR is Valqua's high purity FFKM material. Its low compression set and resistance to adhesion make the FLUORITZ<sup>TM</sup>-TR fit for static applications. Low weight loss and crack-resistance demonstrate the FLUORITZ <sup>TM</sup>-TR's radical resistance.



- Excellent Compression Set and Low Adhesion for Static Applications
- Improved Plasma and Crack Resistance for Harsher Environments

## Applications

- Plasma Enhanced CVD Equipment
- Low Pressure CVD Equipment
- Plasma Etch Equipment

### Contact Us

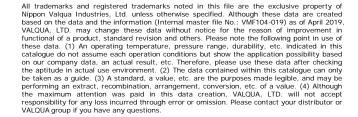
Valqua America, Inc. 4655 Old Ironsides Dr #380 Santa Clara, CA 95054 www.valqua-america.com



## Typical Properties

Color	Dark Brown
Hardness (Shore A)	69
Tensile Strength (MPa)	12.6
Elongation (%)	180
Modulus 100% Elongation (MPa)	2.7
Maximum Temperature (°C)	260
Compression Set (%)	5

Compression Set: 25% compression at 200℃ for 72 hours Values above are actual measurements, not standards





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## Additional information

## FLUORITZ ™-TR

## Performance Properties

## Radical Exposure Test (Anti-cracking property)

**Test Conditions** 

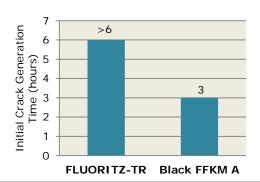
Equipment: Parallel flat plasma tool

Plasma power: RF300W Gas: 02+CF4 (196:4)

Irradiation condition: Down flow attack

Radical Exposure Test (Weight loss)

Test piece: AS568A-214 with 28% stretching condition

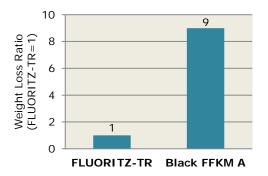


**Test Conditions** 

Equipment: Parallel flat plasma tool

Plasma power: RF300W Gas: O2+CF4 (196:4)

Irradiation condition: 6 hours down flow attack
Test piece: AS568A-214 with 0% stretching condition

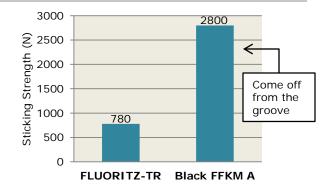


## Sticking Strength

Test Conditions

Temperature: 80°C Heating time: 72h

Test piece: AS568-270 O-ring Counter face: Anodized aluminum



## Inorganic Components Content

**Test Conditions** 

Measuring method: ICP/MS analysis
Inorganic elements: Total of 62 elements

